## **Specification of Thermoelectric Module**

## **TEHC1-12714P**

### Description

The 127couples,  $50\text{mm} \times 50/55\text{mm}$  size module which is made of selected high performance ingot to achieve superior cooling performance and greater delta T up to 74 °C, designed for superior cooling and heating up to 100 °C applications. If higher operation or processing temperature is required, please specify, we can design and manufacture the custom made module according to your special requirements.

#### Features

- No moving parts, no noise, and solid-state
- Compact structure, small in size, light in weight
- Environmental friendly
- RoHS compliant
- Precise temperature control
- Exceptionally reliable in quality, high performance

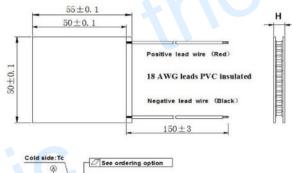
#### **Performance Specification Sheet**

### Application

- Food and beverage service refrigerator
- Portable cooler box for cars
- Liquid cooling
- Temperature stabilizer
- CPU cooler and scientific instrument
- Photonic and medical systems

Th(°C)	27	50	Hot side temperature at environment: dry air, N <sub>2</sub>	
DT <sub>max</sub> (°C)	74	83	Temperature Difference between cold and hot side of the module when cooling capacity is zero at cold side	
U <sub>max</sub> (Voltage)	16.8	18.1	Voltage applied to the module at DT <sub>max</sub>	
I <sub>max(</sub> amps)	14.0	14.0	DC current through the modules at DT <sub>max</sub>	
Q <sub>Cmax</sub> (Watts)	146.2	157.5	Cooling capacity at cold side of the module under DT=0 °C	
AC resistance(ohms)	0.90	0.97	The module resistance is tested under AC	
Tolerance (%)	± 10		For thermal and electricity parameters	

#### Geometric Characteristics Dimensions in millimeters



**Ordering Option** 



- A. Solder:
   B. Sealant:

   1. T100: BiSn (Tmelt=138°C)
   1. NS: No sealing (Standard)

   2. T200: CuAgSn (Tmelt = 217°C)
   2. SS: Silicone sealant

   3. T240: SbSn (Tmelt = 240°C)
   3. EPS: Epoxy sealant
- C. Ceramics:
- 1. Alumina (Al<sub>2</sub>O<sub>3</sub>, white 96%)
- 2. Aluminum Nitride (AlN)

#### Naming for the Module

2. Metalized

**D.** Ceramics Surface Options:

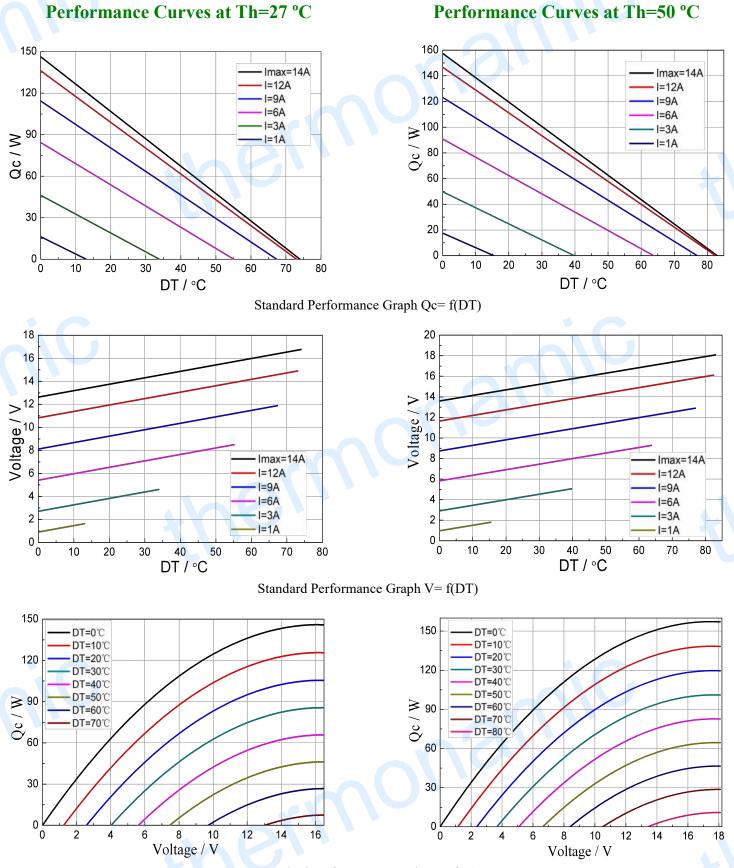
1. Blank ceramics (not metalized)

Suffix	Thickness	Flatness/	Lead wire length(mm)	ТЕНС1-12714Р-х-х-х-х	
(mm)		Parallelism (mm)	Standard/Optional length	T T T Ceramics	
TF	$0:4.2 \pm 0.1$	0:0.1/0.1	150±3/Specify	Flatness/ Parallelism Sealant	
TF	$1:4.2 \pm 0.05$	1:0.05/0.05	150±3/Specify	Solder TEHC1-12714P-T100-NS –TF01 -AIO	
Eg. TF01: Thickness $4.2 \pm 0.1$ (mm) and Flatness $0.05/0.05$ (mm)				T100: BiSn(Tmelt=138°C) NS: No sealing AlO: Alumina (Al2O3, white 96%)	

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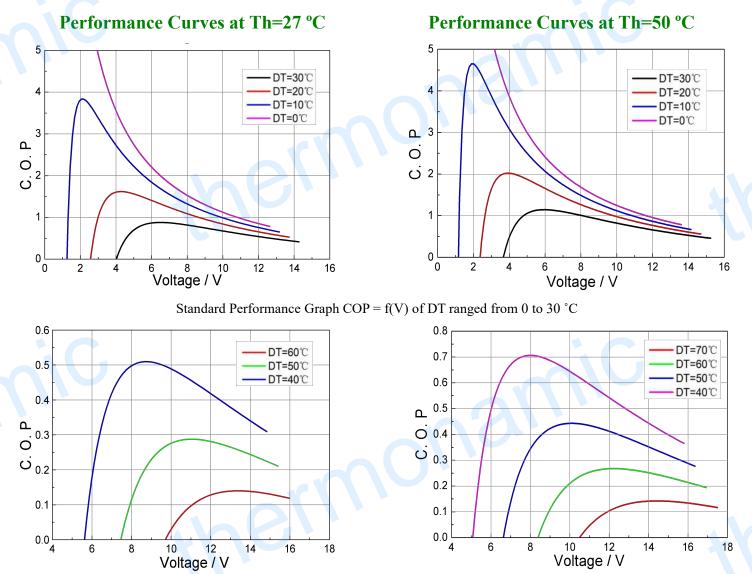


Standard Performance Graph Qc = f(V)

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### **TEHC1-12714P**



Standard Performance Graph COP = f(V) of DT ranged from 40 to 60/70 °C

**Remark:** The coefficient of performance (COP) is the cooling power Qc/Input power ( $V \times I$ ).

#### **Operation Cautions**

- Attach the cold side of module to the object to be cooled
- Attach the hot side of module to a heat radiator for heat dissipating
- Operation below I<sub>max</sub> or V<sub>max</sub>
- Work under DC

Note: All specifications subject to change without notice.